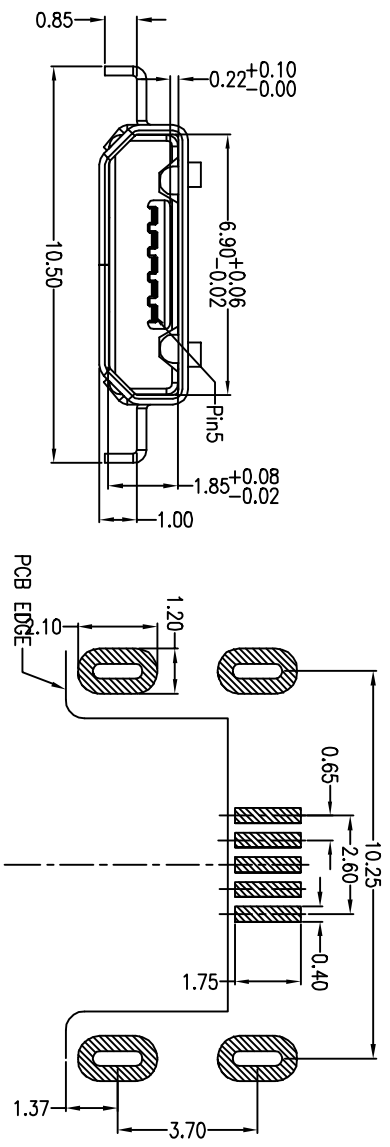
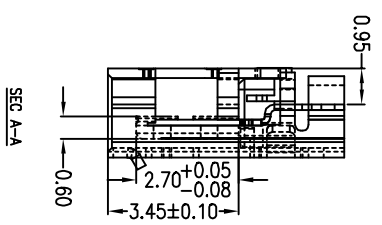
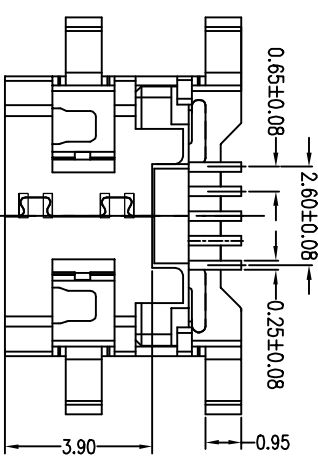
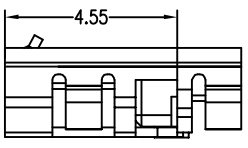
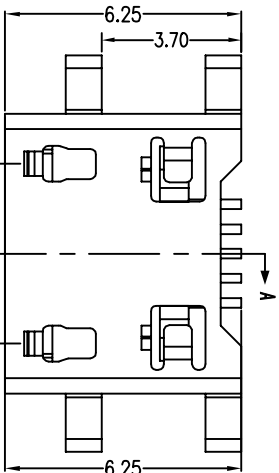
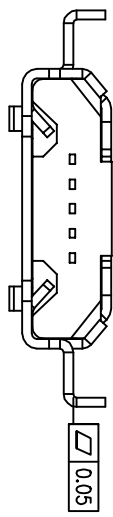


REV.	ECH NO	LOCATIONS	DESCRIPTION	DATE



RECOMMENDED PCB LAYOUT

PCB图仅供参考

- Note:
1. Material:
 - 1.1 Housing: High temperature thermoplastic with g.f.I,UL94V-0
 - 1.2 Contact: copper alloy,t=0.15mm
 - 1.3 Shell: copper alloy,t=0.25mm
- 2.Specification:
- 2.1 Current rating: 1 A Max. voltage: 100 V(ac) for 1 min.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 MΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min.
 - 2.7 Temperature range: -30°C~80°C

A 01 S B 1 4 1 B 3-401

- ① 产品代号 A:成品
- ② 产品系列 01:Micro usb 5pin
- ③ 产品类别 S:母座
- ④ 产品类型 B:B TYPE
- ⑤ 外壳材质 1:CS300R-H
- ⑥ 端子材质 4:05181R-EH
- ⑦ 主体材质 1:LP
- ⑧ 主体颜色 B:黑色
- ⑨ 下板类型 3:沉板式
- ⑩ 细节序号 401:Micro usb 5s B Type Smt无接地片沉板式1.0无导位

PART NO:	A01SB141B3-401	MATERIAL:	SEE NOTE
MODEL NO:	XX	FINISH:	SEE NOTE
UNIT:	MM	SIZE:	A4
TOLERANCE UNSPECIFIED		DR:	xiaoyouhong
.x	0.15	CHK:	
.xx	0.10	APP:	
.xxx	0.05		
Ang	1°		

深圳扬讯电子有限公司

TITLE: Micro usb 5s B Type Smt无接地片沉板式1.0无导位

DWG NO:	A401	REV:	A
SCALE:	5:1	DATE:	2014.04.24

